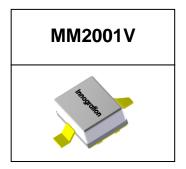
10W, 50V High Power RF LDMOS FETs

Description

The MM2001V is a 10-watt, highly rugged, unmatched LDMOS FET, designed for wide-band commercial and industrial applications at frequencies up to 2 GHz. It can be used in Class AB/B and Class C for all typical modulation formats.

Typical Performance (On Innogration fixture with device soldered):
 V_{DD} = 48 V, I_{DQ} = 10 mA, Pulse CW, Pulse Width=10uS, Duty Cycle=10%.

Freq(MHz)	P _{1dB} (dBm)	G _P @P _{1dB} (dB)	P _{3dB} (dBm)	η _D @Ρ _{3dB} (%)
960	43.7	15.3	44.4	55.3
1000	43.8	15.6	44.5	56.6
1050	44.3	15.5	44.8	58.2
1100	44.4	16.4	44.8	59.3
1150	44.2	16.4	44.7	59.6
1200	44.1	16.9	44.5	60.4
1250	43.9	16.7	44.3	60.3
1300	43.6	16.8	44.2	60.5
1350	43.4	16.6	44.0	61.0
1400	43.2	16.0	43.8	59.6



Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCI drift

Suitable Applications

- 30-88MHz (Ground communication)
- 54-88MHz (TV VHF I)
- 88-108MHz (FM)
- 118 -140MHz (Avionics)
- 960-1215MHz (Avionics)

Table 1. Maximum Ratings

- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant
- 136-174MHz (Commercial ground communication)
- 160-230MHz (TV VHF III)
- 30-512MHz (Jammer, Ground/Air communication)
- 470-860MHz (TV UHF)

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	+110	Vdc
GateSource Voltage	V _{gs}	-10 to +10	Vdc
Operating Voltage	V _{DD}	+50	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	TJ	+225	°C

Table 2. Thermal Characteristics

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Characteristic	Characteristic Syr					Unit	
Thermal Resistance, Junction to Case							
T _C = 85°C, T _J =200°C, DC test	KelC	өјс 3			°C/W		
Table 3. ESD Protection Characteristics		I			1		
Test Methodology		Class					
Human Body Model (per JESD22A114)			Class 2				
Table 4. Electrical Characteristics (TA = 25 $^{\circ}$ C unless of	herwise	noted)					
Characteristic		Symbol	Min	Тур	Max	Unit	
DC Characteristics							
Drain-Source Voltage		N		445		M	
V _{GS} =0, I _{DS} =1.0mA		V _{(BR)DSS}		115		V	
Zero Gate Voltage Drain Leakage Current					1		
$(V_{DS} = 90V, V_{GS} = 0 V)$		DSS				μΑ	
Zero Gate Voltage Drain Leakage Current					1	μA	
$(V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V})$		DSS				μΛ	
GateSource Leakage Current	GateSource Leakage Current					۸	
$(V_{GS} = 10 \text{ V}, V_{DS} = 0 \text{ V})$		GSS			1	μA	
Gate Threshold Voltage		V _{GS} (th)		2.82		V	
$(V_{DS} = 50V, I_{D} = 600 \ \mu A)$		V GS(UI)				v	
Gate Quiescent Voltage		V _{GS(Q)}		3.0		V	
(V_{DD} = 48 V, I_D = 10 mA, Measured in Functional Test)		V GS(Q)	Min	0.0		v	
Common Source Input Capacitance		C _{ISS}		11.4		pF	
(V _{GS} = 0V, V _{DS} =40 V, f = 1 MHz)	OISS		11.4		рі		
Common Source Output Capacitance	Coss		4.9		pF		
(V _{GS} = 0V, V _{DS} =40 V, f = 1 MHz)	0055		ч.0		P1		
Common Source Feedback Capacitance	C _{RSS}		0.05		pF		
$(V_{GS} = 0V, V_{DS} = 40 V, f = 1 MHz)$	C K35						
Load Mismatch (In Innogration Test Fixture, 50 ohm system): $V_{DD} = 48 \text{ Vdc}, I_{DQ} = 10 \text{ mA}, f = 2000 \text{ MHz}$							
VSWR 10:1 at 10W pulse CW Output Power	VSWR 10:1 at 10W pulse CW Output Power						

Reference Circuit of Test Fixture Assembly Diagram

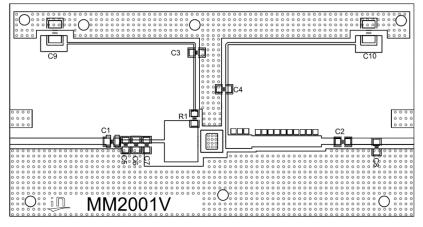


Figure 1. Test Circuit Component Layout

 Table 5. Test Circuit Component Designations and Values

Part	description	Model			
C1,C2,C3,C4	33pF	ATC600F			
C5	2pF	ATC600F			
C6,C7,C8	1pF	ATC600F			
C9,C10	10uF				
R1	10 ohm				
РСВ	0.508mm [0.020"] thick, εr=3.48, Rogers RO4350B, 1 oz. copper				

TYPICAL CHARACTERISTICS

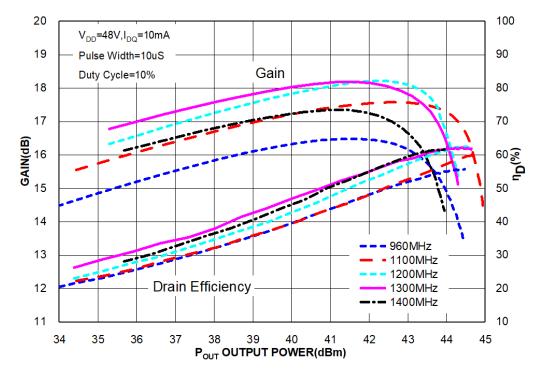
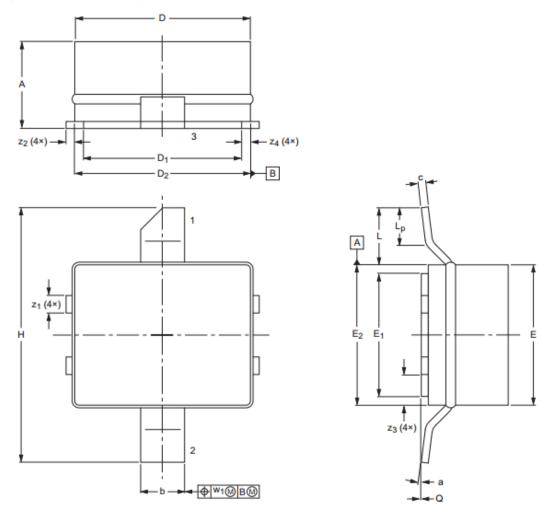


Figure 2. Power Gain and Drain Efficiency as function of Power Out

Package Outline

Earless Flanged ceramic package; 2 leads(1-Drain,2-Gate,3-Source)



0 2.5 5 mm scale

UNIT	Α	b	с	D	D1	E	E1	E ₂	Н	L	Lp	Q	W ₁	Z 1	Z 2	Z 3	Z 4	α
	2.34	1.35	0.23	5.16	4.65	4.14	3.63	4.14	7.49	2.03	1.02	0.1	0.05	0.58	0.25	0.97	0.51	7°
mm	2.13	1.19	0.18	5.00	4.50	3.99	3.48	3.99	7.24	1.27	0.51	0.0	0.25	0.43	0.18	0.81	0.00	0°

OUTLINE		REFERENCE	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
PKG-MM				$\square \oplus$	18/6/2014

Revision history

Table 6. Document revision history

Date	Revision	Datasheet Status
2019/11/18	Rev 1.0	Preliminary Datasheet

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